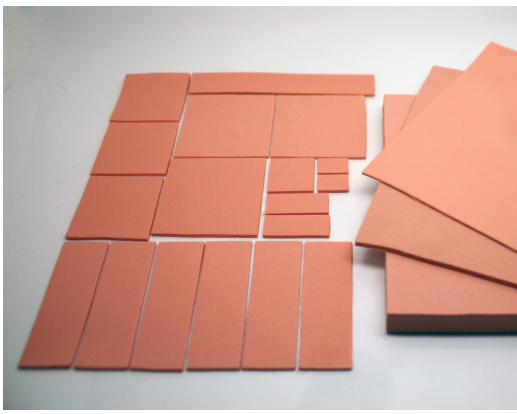
Thermally Conductive Gap Filler Pad

THERM-A-GAP™ MCS30

Highly Conformable/Low Silicone Extractable Thermal Pad

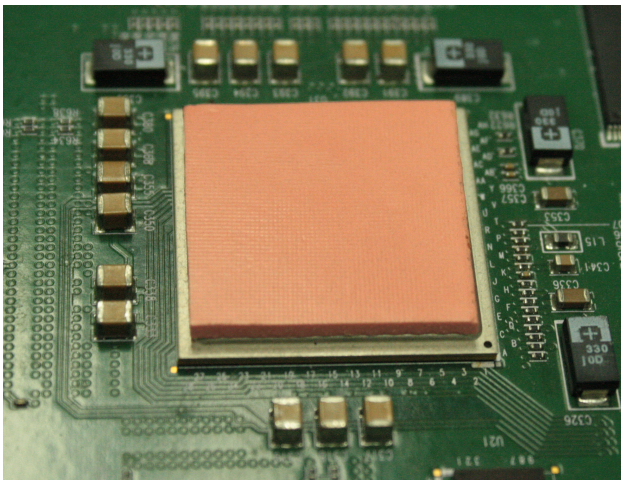


Customer Value Proposition:

THERM-A-GAP™ MCS30 is a series of soft, low weight-loss and fully cured thermal pad. The cross-linked soft gel structure provides superior performance and long term thermal stability over conventional high modulus thermal pads. This material is designed to be used in applications requiring low compression forces.

THERM-A-GAP™ MCS30 is a thermal interface material design for low deflection force applications with moderate thermal conductivity and high reliability. It is ultra soft and with two natural tack sides it allows for easy handling, and can conform to irregular surfaces.

THERM-A-GAP™ MCS30 exhibits superior long term physical and thermal reliability. This material demonstrates resistance to the thermal oxidation degradation associated with continuous application temperatures of up to 200ºC.



Contact Information:

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Fax: +86 21 28995146
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Products Features:

- Thermal conductivity : 3W/m-K
- Highly conformable, ultra soft
- Low silicone extractable
- Low outgassing
- Electrically isolating

Typical Applications:

- Desktop computers, laptops, servers
- Telecommunications equipment
- Consumer electronics
- Automotive electronics
- Memory modules

Order Information:

Therm-A-Gap™ pads are available in the following formats.
Distributor sheets-Typically 18″×18″

0.020″ =69-11-20698-MCS30X	0.030″ =69-11-20913-MCS30X
0.040″ =69-11-20684-MCS30X	0.050″ =69-11-27072-MCS30X
0.060″ =69-11-20991-MCS30X	0.070″ =69-11-20685-MCS30X
0.080″ =69-11-21259-MCS30X	0.100″ =69-11-20672-MCS30X
0.120″ =69-11-27102-MCS30X	0.130″ =69-11-20675-MCS30X
0.160″ =69-11-20686-MCS30X	0.200″ =69-11-20687-MCS30X

Custom thicknesses available upon request.
"X" represents carrier, like "G" = Glass fiber, "GL" = Improved clean-break glass fiber, or " " = Non-carrier.
Contact Chomerics for detail carrier information and thickness availability.

Parker Chomerics

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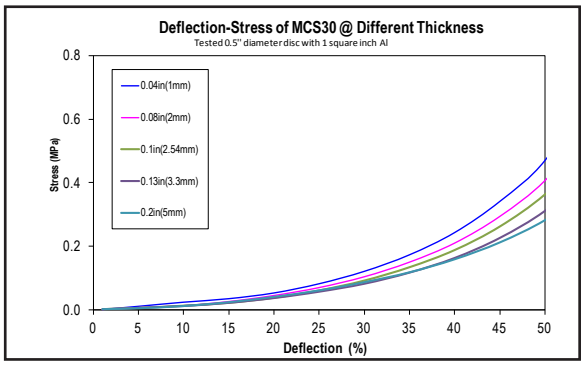
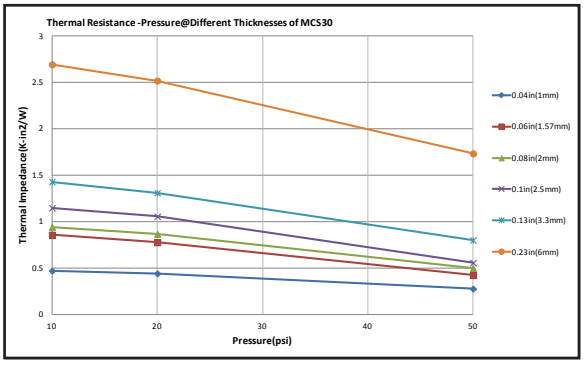
Typical Properties	MCS 30	Test Method
Color	Pink	Visual
Specific Gravity	2.9	ASTM D792
Standard Thicknesses, mm(inch)	0.5-5.0 (0.02-0.200)*1	ASTM D374
Hardness, Shore OO	25	ASTM D2240
Operating Temperature Range, °C	-50 to 200	--
Leachable silicone, %	0.25	TM-CDA-RND-0021-A*2
Thermal Conductivity, W/m-K@20psi	3.0	ASTM D5470
Thermal Impedance,(°C-in^2/w) @20psi, @1mm thickness	0.4	ASTM D5470
Heat Capacity, J/g-K	0.83	ASTM E1269
Coefficient of Thermal Expansion, ppm/K	28.8(70°C-130°C)	ASTM E831
Dielectric Strength, KVac/mm	11	ASTM D149
Volume Resistivity, ohm-cm	10^{15}	ASTM D257
Outgassing, % TML	0.06	ASTM E595
Flammability Rating(See UL File E140244 for Details)(Internal Test)	V-0	UL 94
RoHS Compliant	Yes	Chomerics Certification
Shelf Life, months from date of manufacture	24	Chomerics

*1 Thickness tolerance, mm (in.) ±10% nominal thickness @ 2.5mm (100mil) or less; ±0.25mm (10mil) @ nominal thickness greater than 2.5 mm (100mil). Custom thicknesses may be available upon request.

*2 Test method: 0.1 in thickness, 1 in dia. Probe, compress 50%, 125°C ×24hrs.





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